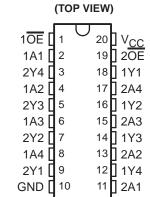
SCLS582B - APRIL 2004 - REVISED APRIL 2008

- Qualified for Automotive Applications
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17

description/ordering information

This octal buffer/driver is designed specifically to improve the performance and density of 3-state memory-address drivers, clock drivers, and bus-oriented receivers and transmitters.

The SN74AHCT240 device is organized as two 4-bit buffers/line drivers with separate output-enable (\overline{OE}) inputs. When \overline{OE} is low, the device passes data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.



PW PACKAGE

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ shall be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION[†]

TA	PACKA	GE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP - PW	Tape and reel	SN74AHCT240IPWRQ1	AHCT240I

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION TABLE (each 4-bit buffer/driver)

INP	JTS	OUTPUT
OE	Α	Υ
L	Н	L
L	L	Н
Н	Χ	Z

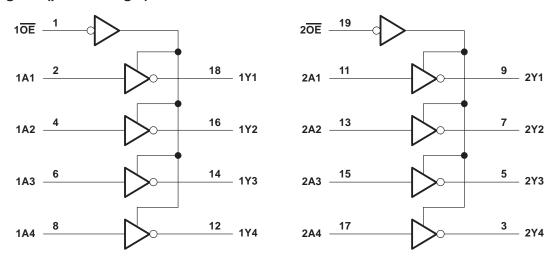


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Note 1) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) Continuous output current, I_O ($V_O = 0$ to V_{CC}) Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2)	$\begin{array}{cccccccccccccccccccccccccccccccccccc$
Package thermal impedance, θ_{JA} (see Note 2)	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
٧ _I	Input voltage	0	5.5	V
٧o	Output voltage	0	VCC	V
ІОН	High-level output current		-8	mA
loL	Low-level output current		8	mA
TA	Operating free-air temperature	-40	85	°C

All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST SOMETIONS	\ ,,	T,	ղ = 25°C	;	MIN	B4 A 3/	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIIN	MAX	UNIT
V	I _{OH} = -50 μA	451/	4.4	4.5		4.4		V
VOH	I _{OH} = -8 mA	4.5 V	3.94			3.8		
	$I_{OL} = 50 \mu A$	451/			0.1		0.1	V
VOL	I _{OL} = 8 mA	4.5 V			0.36		0.44	
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±2.5	μΑ
Ц	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40	μΑ
ΔICC [†]	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		2.5	10	·	10	pF
Co	$V_O = V_{CC}$ or GND	5 V		3				pF

[†] This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or VCC.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T	λ = 25°C	;		B4 A V	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
^t PLH	^	Υ	C: 15 pF		5.4	7.4	1	8.5	20
^t PHL	А	Ť	C _L = 15 pF		5.4	7.4	1	8.5	ns
^t PZH	<u> </u>	Y	C. 15 nF		7.7	10.4	1	12	20
^t PZL	OE	Ť	C _L = 15 pF		7.7	10.4	1	12	ns
^t PHZ	<u>OE</u>	Y	C _L = 15 pF		8.3	10.4	1	12	ns
^t PLZ	OE	'	OL = 13 pi		8.3	10.4	1	12	113
^t PLH	•	.,	0 50 5		5.9	8.4	1	9.5	ns
t _{PHL}	А	Y	C _L = 50 pF		5.9	8.4	1	9.5	
^t PZH	ŌĒ	.,	0 50 5		8.2	11.4	1	13	
^t PZL	OE	Y	C _L = 50 pF		8.2	11.4	1	13	ns
t _{PHZ}	ŌĒ	V	0 50-5		8.8	11.4	1	13	
tPLZ	OE	Y	C _L = 50 pF		8.8	11.4	1	13	ns
tsk(o)			C _L = 50 pF			1		1	ns

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
VOH(V)	Quiet output, minimum dynamic VOH		4.1		V
V _{IH(D)}	High-level dynamic input voltage	2			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.8	V

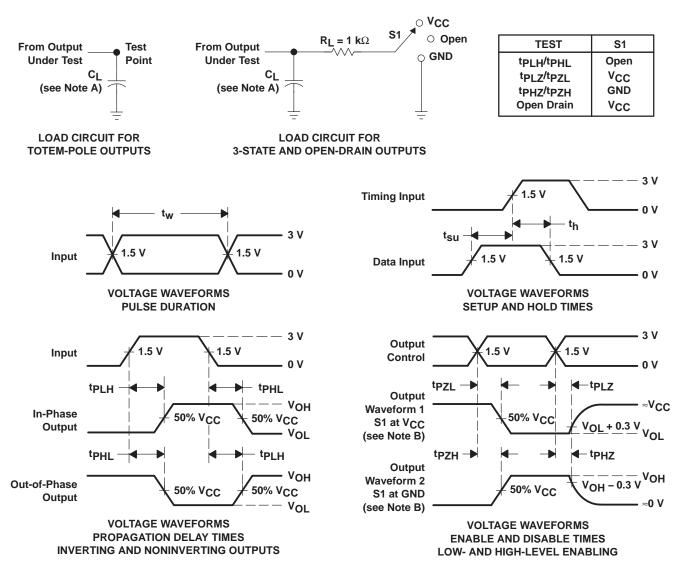
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	10	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 3 \text{ ns}$, $t_f \le 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM



10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CAHCT240IPWRG4Q1	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT240I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74AHCT240-Q1:



PACKAGE OPTION ADDENDUM

10-Dec-2020

● Catalog: SN74AHCT240

• Military: SN54AHCT240

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

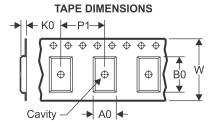
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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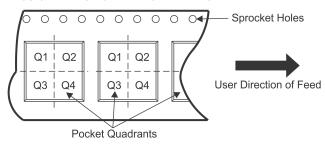
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CAHCT240IPWRG4Q1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CAHCT240IPWRG4Q1	TSSOP	PW	20	2000	853.0	449.0	35.0	

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



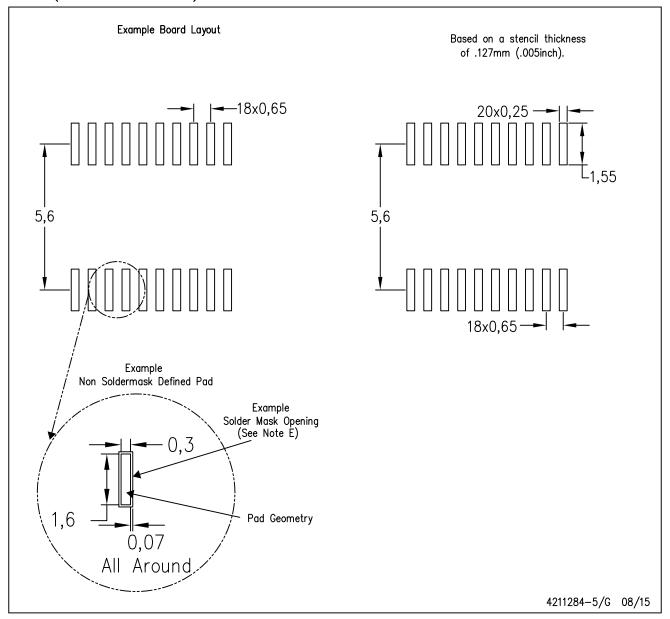
NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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